

TITLE OF THE INVENTION: PROTECTIVE FILM COMPOSITION,
MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE, AND LASER
CUTTING METHOD

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ABSTRACT

The invention provides a protective film composition including: a water-soluble resin (A), a laser light absorbing agent (B), and a solvent (C), wherein the water-soluble resin (A) contains a polyvinylpyrrolidone-based water-soluble resin (A-1), and the polyvinylpyrrolidone-based water-soluble resin (A-1) has a K value of 75 or more and
10 150 or less. The protective film composition has the advantage of good leveling property.